

# RV8L002SN HZG

Nch 60V 250mA Small Signal MOSFET

## **AEC-Q101 Qualified**

$V_{DSS}$	60V
R <sub>DS(on)</sub> (Max.)	2.4Ω
I <sub>D</sub>	±250mA
P <sub>D</sub>	1.0W

# ● Features

- 1) Leadless ultra small and exposed drain pad for excellent thermal conduction SMD plastic package (1.0×1.0×0.4mm)
- 2) Side wettable Flanks for automated optical solder inspection(AOI).

Tin-plated 100% solderable side pads guarantees Min.125µm

- 3) AEC-Q101 Qualified.
- 4) ESD protection up to 2kV (HBM)
- 5) Very fast switching
- 6) Ultra low voltage drive (2.5V drive)

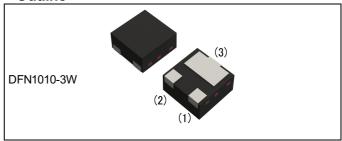
## Application

Switching circuits

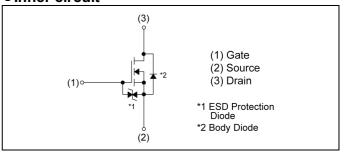
Low-side loadswitch

Relay driver

### Outline



## •Inner circuit



Packaging specifications

	Packing	Embossed Tape
Туре	Reel size (mm)	180
	Tape width (mm)	8.0
	Quantity (pcs)	8000
	Taping code	G2CR
	Marking	RKU

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	$V_{DSS}$	60	V
Continuous drain current	I <sub>D</sub>	±250	mA
Pulsed drain current	I <sub>DP</sub> *1	±1.0	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Power dissipation	P <sub>D</sub> *2	1.0	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Parameter	Cymahal	Values			l le:t
	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R <sub>thJA</sub> *2	-	-	125.0	°C/W

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Symbol Conditions —		Values			Unit
Parameter			Min.	Тур.	Max.	UTIIL
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	60	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	63.7	-	mV/°C
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = 10V, I_{D} = 1mA$	1.0	-	2.3	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-2.8	-	mV/°C
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 250mA	-	1.7	2.4	
Static drain - source	D *4	$V_{GS} = 4.5V, I_D = 250mA$	-	2.1	3.0	Ω
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4.0V, I <sub>D</sub> = 250mA	-	2.3	3.2	12
		$V_{GS} = 2.5V, I_D = 10mA$	-	3.0	12.0	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 10V, I <sub>D</sub> = 250mA	250	-	-	mS

<sup>\*1</sup> Pw≦10µs , Duty cycle≦1%

\*4

\*5

<sup>\*2</sup> Mounted on a Cu board (40mm×40mm×0.8mm)

<sup>\*3</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Parameter	Symbol Conditions —	Canditions	Values			Unit
Parameter		Min.	Тур.	Max.	Offit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	15	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	4.5	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	2	-	
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 30V,V <sub>GS</sub> = 10V	-	3.5	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 100mA	-	5	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 300\Omega$	-	18	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	28	-	

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Cumb ol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offit
Continuous forward current	Is	T - 25°C	-	-	250	mA
Pulse forward current	I <sub>SP</sub> *1	T <sub>a</sub> = 25℃	-	-	1.0	Α
Forward voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 250 \text{mA}$	-	-	1.2	V

### Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

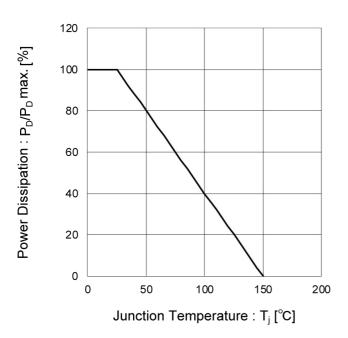
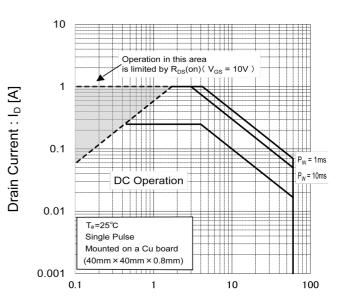


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

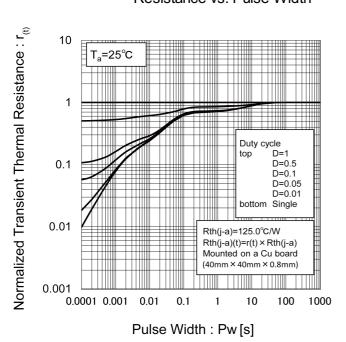
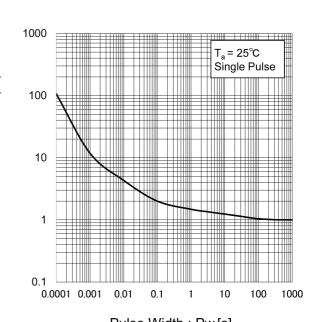


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Peak Transient Power: P(W)

### Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

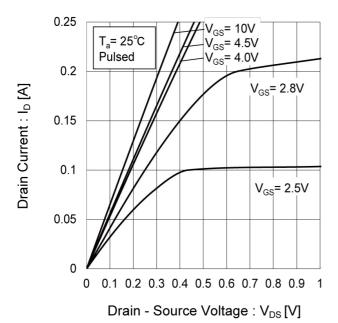


Fig.6 Typical Output Characteristics(II)

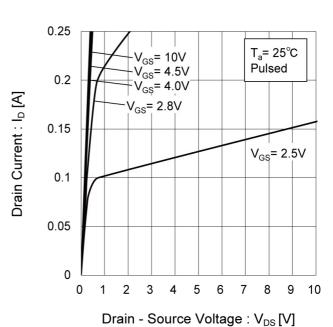
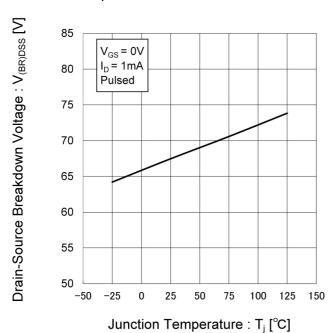


Fig.7 Breakdown Voltage vs. Junction Temperature





## • Electrical characteristic curves

Fig.8 Typical Transfer Characteristics

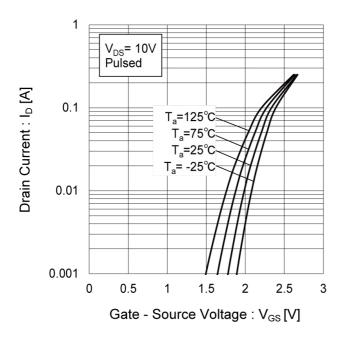


Fig.9 Gate Threshold Voltage vs. Junction Temperature

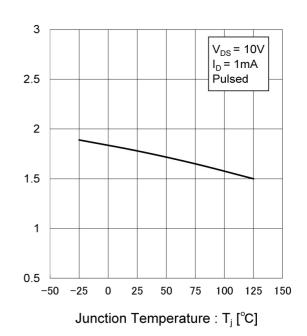
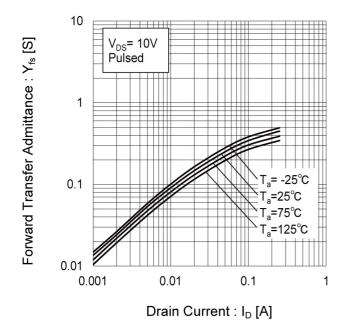


Fig.10 Forward Transfer Admittance vs. Drain Current



Gate Threshold Voltage: V<sub>GS(th)</sub> [V]

### Electrical characteristic curves

Fig.11 Drain Current Derating Curve

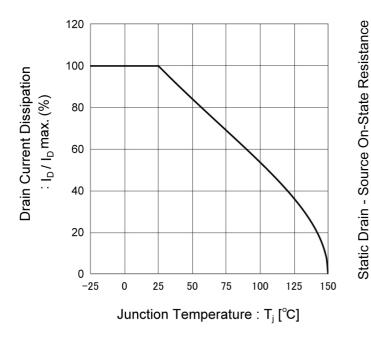


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

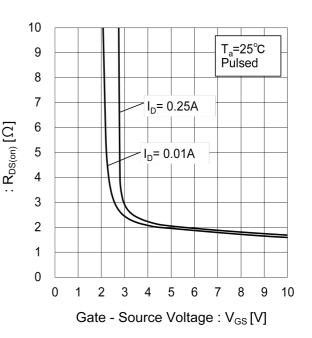


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

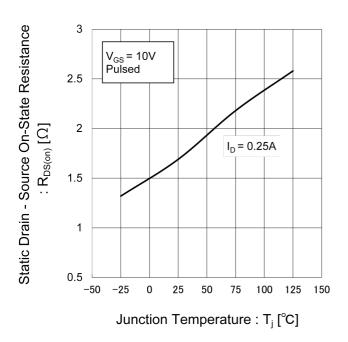
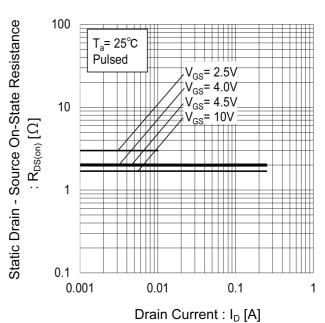


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)



### Electrical characteristic curves

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

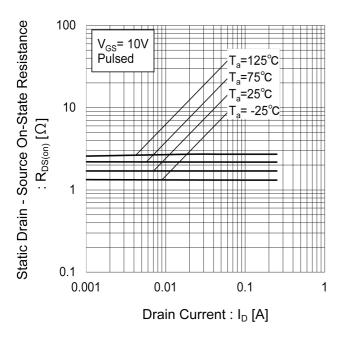


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

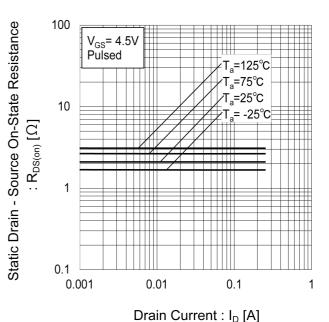


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

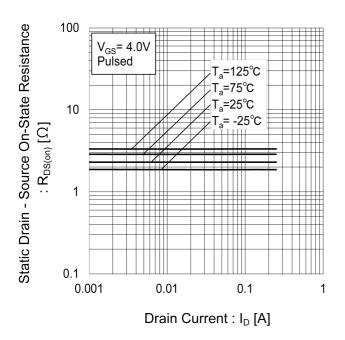
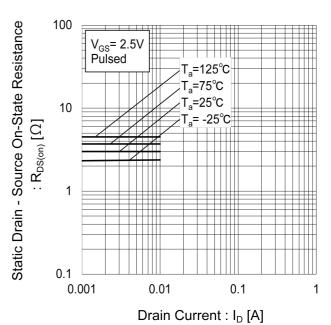


Fig.18 Static Drain - Source On - State Resistance vs. Drain Current(V)



## • Electrical characteristic curves

Fig.19 Typical Capacitance vs. Drain - Source Voltage

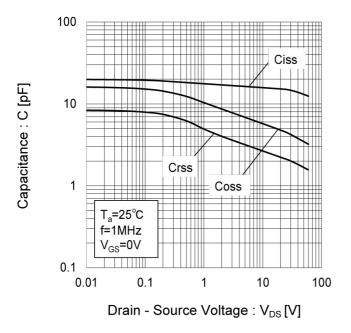


Fig.20 Switching Characteristics

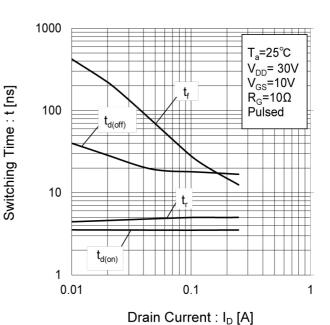
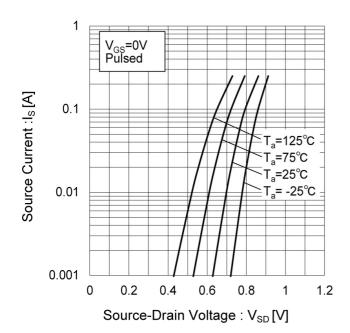


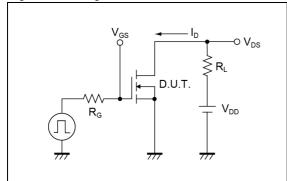
Fig.21 Source Current vs. Source Drain Voltage

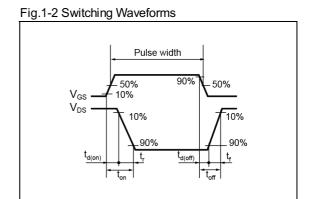


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## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit



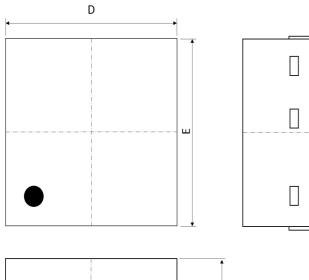


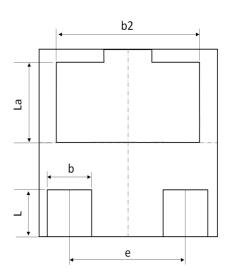
## Notice

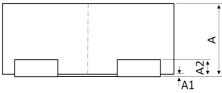
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

## Dimensions

## **DFN1010-3W**







DIM	MILIMI	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.35	0.45	0.014	0.018
A1	0.00	0.03	0.000	0.001
A2	0.125	_	0.005	_
b	0.20	0.30	0.008	0.012
b2	0.70	0.90	0.028	0.035
D	0.95	1.05	0.037	0.041
E	0.95	1.05	0.037	0.041
е	0.0	65	0.0	26
L	0.20	0.30	0.008	0.012
La	0.40	0.50	0.016	0.020

Dimension in mm/inches

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JÁPAN	JÁPAN USA		CHINA
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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#### **Precautions Regarding Application Examples and External Circuits**

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

## **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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